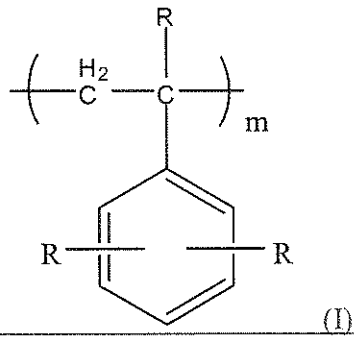
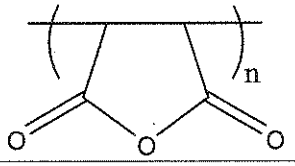
where each m, n and r is independently a real number that represents a mole fraction of the respective constitutional unit in the terpolymer, each R is independently a hydrogen, an aromatic group or an aliphatic group, Ar is an aromatic radical, and where the epoxy group to the second constitutional unit has a molar ratio in a range of 1.0:1.0 to 2.7:1.0.

[005a] In a first aspect of the present disclosure, there is provided a curable composition, comprising: an epoxy resin; and a hardener compound for curing with the epoxy resin, the hardener compound comprising: a terpolymer having a first constitutional unit of the formula (I):



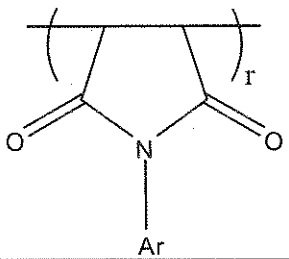
(I)

a second constitutional unit of the formula (II):



(II)

and a third constitutional unit of the formula (III):



(III)

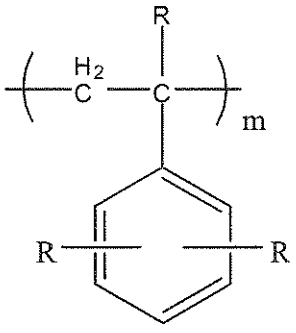
where each m, n and r is independently a real number that represents a mole fraction of the respective constitutional unit in the terpolymer, each R is independently a hydrogen, an aromatic group or an aliphatic group, Ar is an aromatic radical, and where the epoxy group to the second constitutional unit has a molar ratio in a range of 1.0:1.0 to 2.7:1.0.

[006] For the various embodiments, the curable composition does not contain a cyanate group. For the various embodiments, a cured product of the curable composition has a glass transition temperature of at least 150 degrees Celsius (°C). For the various embodiments, the cured product of the curable composition has a dielectric constant (Dk) of 3.1 or less at a frequency of 1 gigahertz (GHz) and a dissipation factor (Df) of 0.01 or less at a frequency of 1 Ghz.

[007] In a second aspect~~The embodiments~~ of the present disclosure~~ also include~~, there is provided a prepreg that includes a reinforcement component and the curable composition, as described herein.

[008] The embodiments of the present disclosure further include an electrical laminate structure that includes a reaction product of the curable composition, as described herein.

[009] Additionally, embodiments of the present disclosure also include a method of preparing a curable composition that includes providing an epoxy resin, and reacting the epoxy resin with a hardener compound, the hardener compound including a terpolymer having a first constitutional unit of the formula (I):



(I)